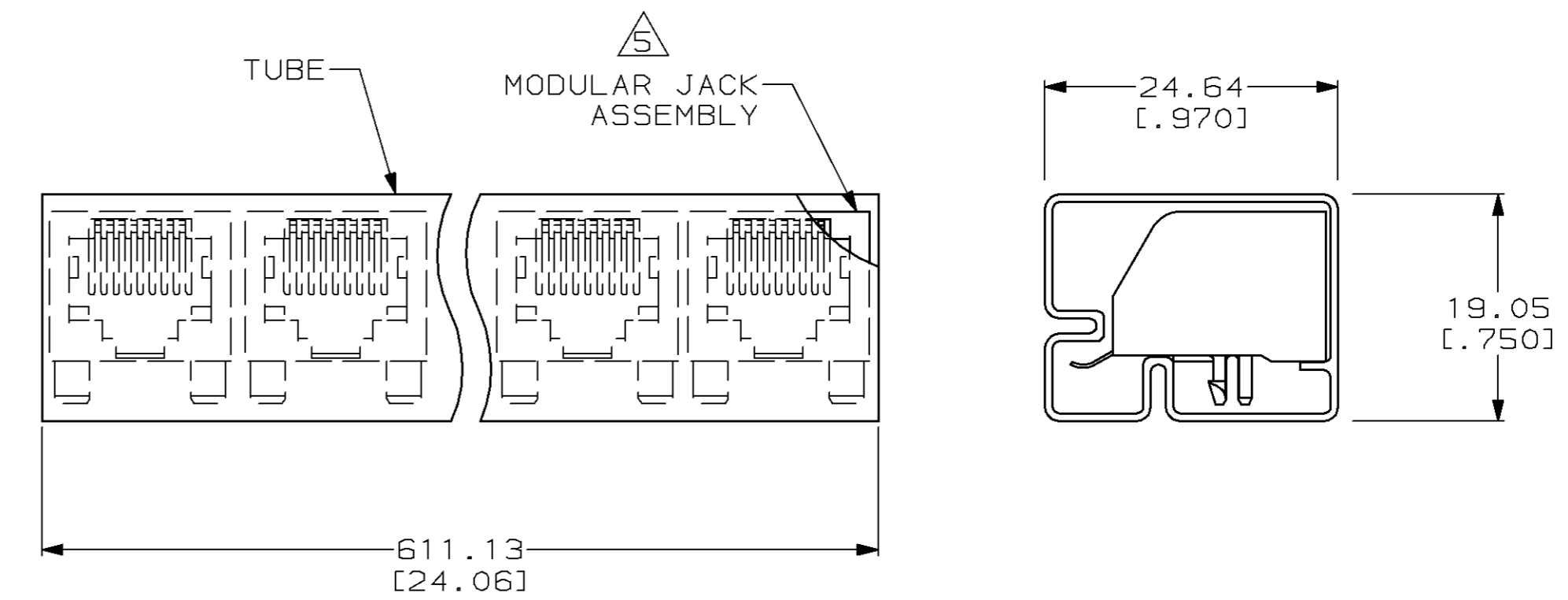
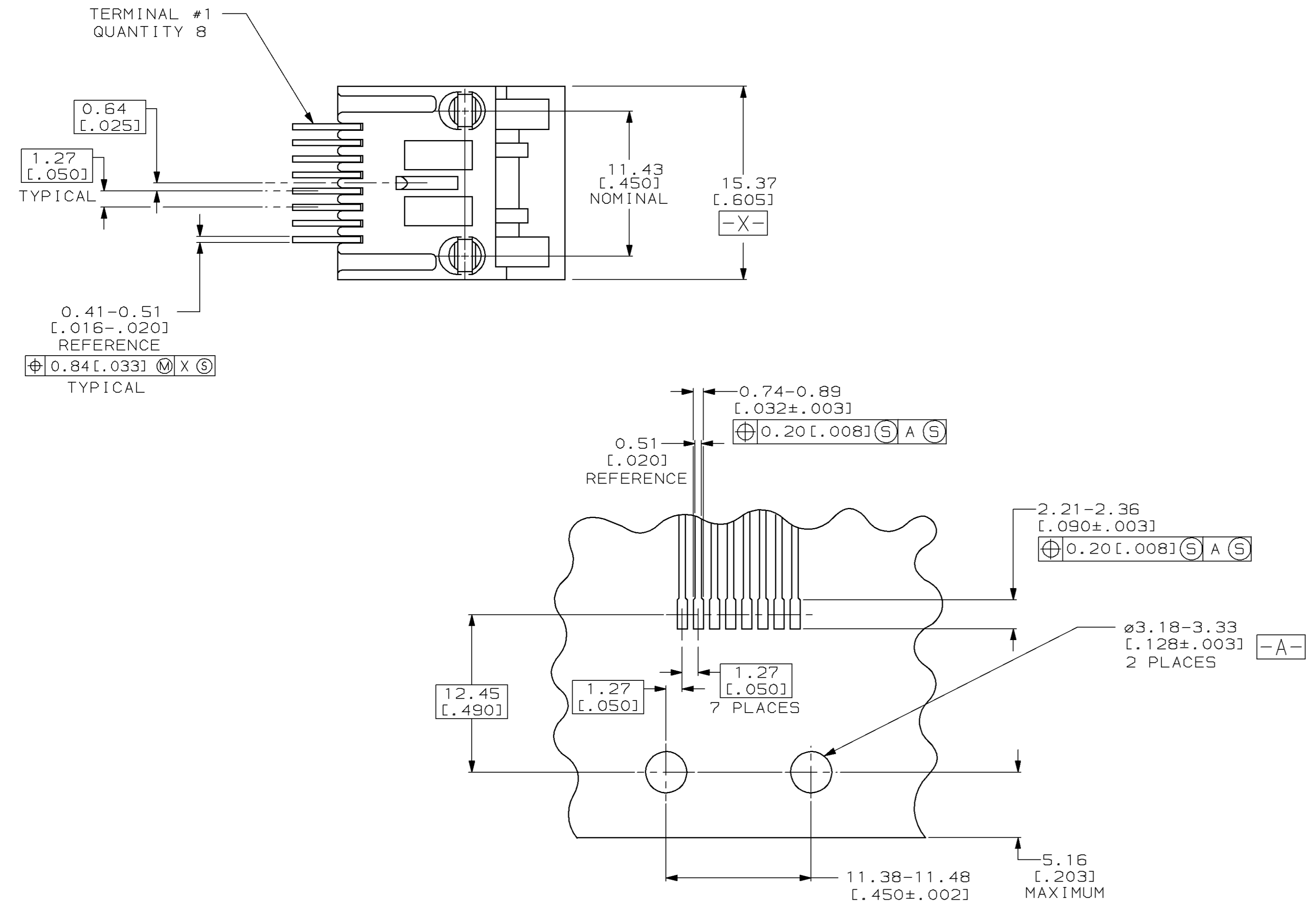
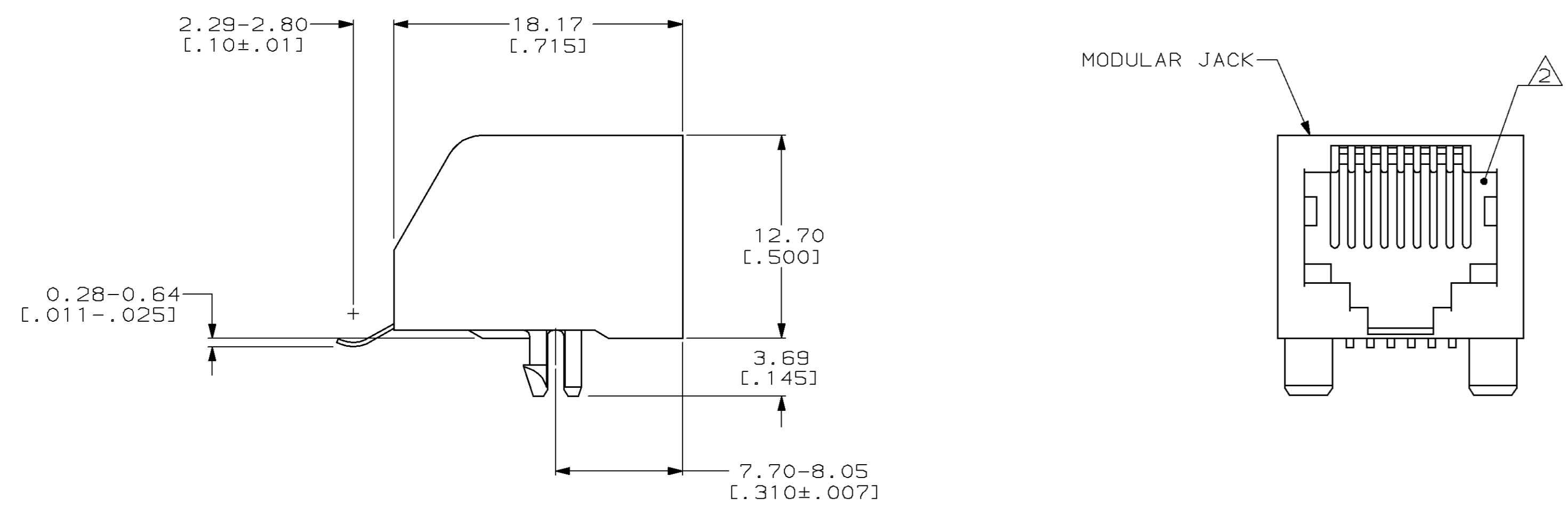


LOC		DIST		P		F		ZONE		LTR		REVISIONS		DATE	APPD
AA	22												REV; EC 0502-0711-97	23OCT97	05 EL

- △ MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 V0, BLACK.
 TERMINAL - 0.36 [0.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [0.00050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [0.00150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [0.00050] MINIMUM THICK NICKEL UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- 4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [0.062±.005] THICK PRINTED CIRCUIT BOARD.
- △ ASSEMBLIES ARE PACKAGED 36 IN A TUBE.
- △ ASSEMBLIES ARE BULK PACKAGED.



DETAIL A
SCALE 2:1

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT

5		8		555764-3	
6		8		555764-1	
PACKAGED		NUMBER OF TERMINALS		PART NO	
DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON:		DR 9-28-95 D. STRAUSSER		AMP AMP Incorporated Harrisburg, PA 17105-3608	
2 PLC DEC ± -		CHK 10-17-95 N. JONES			
3 PLC DEC ± -		APPD 10-23-95 J. TONEY			
MATERIAL		APPD 10-24-95 H. MCGRATHS		NAME	
△		PRODUCT SPEC 108-1163		MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT	
FINISH		APPLICATION SPEC 114-6040		SIZE	
△		WEIGHT -		D 00779	
				DRAWING NO	
				C=555764	
				SCALE 4:1	
				SHEET 1 OF 1	

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.